

Product Summary

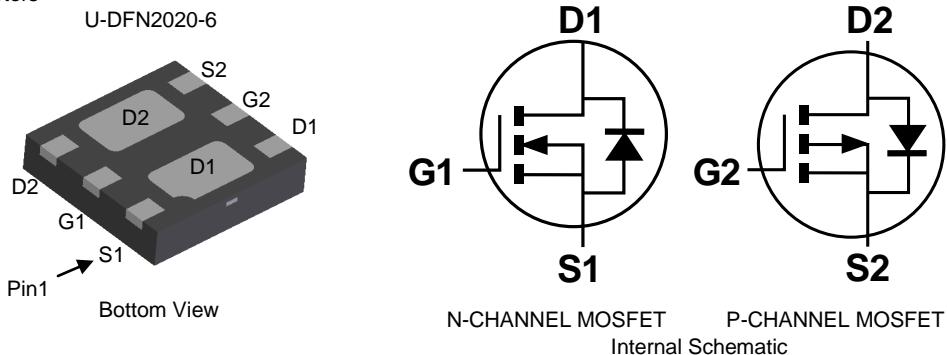
Device	$V_{(BR)DSS}$	$R_{DS(ON)} \text{ max}$	$I_D \text{ MAX}$ $T_A = +25^\circ\text{C}$
Q1 N-Channel	12V	29mΩ @ $V_{GS} = 4.5\text{V}$	5.6A
		34mΩ @ $V_{GS} = 2.5\text{V}$	5.1A
		44mΩ @ $V_{GS} = 1.8\text{V}$	4.5A
		65mΩ @ $V_{GS} = 1.5\text{V}$	3.7A
Q2 P-Channel	-12V	61mΩ @ $V_{GS} = -4.5\text{V}$	-3.8A
		81mΩ @ $V_{GS} = -2.5\text{V}$	-3.3A
		115mΩ @ $V_{GS} = -1.8\text{V}$	-2.8A
		210mΩ @ $V_{GS} = -1.5\text{V}$	-2.3A

Description

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- Power Management Functions
- Portable Power Adaptors



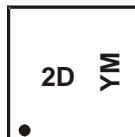
Ordering Information (Note 4)

Part Number	Case	Packaging
DMC1029UFDB -7	U-DFN2020-6	3000/Tape & Reel
DMC1029UFDB -13	U-DFN2020-6	10000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



2D = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: B = 2014)
M = Month (ex: 9 = September)

Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020					
Code	B	C	D	E	F	G	H					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Units
Drain-Source Voltage			V_{DSS}	12	-12	V
Gate-Source Voltage			V_{GSS}	± 8	± 8	V
Continuous Drain Current (Note 5) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	5.6 4.4	-3.8 -3.0	A
	$t < 5\text{s}$	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	7.2 5.8	-5.0 -4.0	A
Maximum Continuous Body Diode Forward Current (Note 5)			I_S	1	-1	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)			I_{DM}	20	-15	A
Avalanche Current (L = 0.1mH)			I_{AS}	15	-12	A
Avalanche Energy (L = 0.1mH)			E_{AS}	12	8	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	Steady State	P_D	1.4	W
	$t < 5\text{s}$		2.2	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	91	°C/W
	$t < 5\text{s}$		55	
Thermal Resistance, Junction to Case		$R_{\theta JC}$	20	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Note: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.

Electrical Characteristics Q1 N-CHANNEL (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	12	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	1.0	μA	$\text{V}_{\text{DS}} = 12\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$\text{V}_{\text{GS}} = \pm 8\text{V}$, $\text{V}_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$\text{V}_{\text{GS(TH)}}$	0.4	—	1	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$, $\text{I}_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	—	17	29	mΩ	$\text{V}_{\text{GS}} = 4.5\text{V}$, $\text{I}_D = 5\text{A}$
		—	20	34		$\text{V}_{\text{GS}} = 2.5\text{V}$, $\text{I}_D = 4.6\text{A}$
		—	24	44		$\text{V}_{\text{GS}} = 1.8\text{V}$, $\text{I}_D = 4.1\text{A}$
		—	30	65		$\text{V}_{\text{GS}} = 1.5\text{V}$, $\text{I}_D = 2\text{A}$
Diode Forward Voltage	V_{SD}	—	0.6	1.2	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_S = 1\text{A}$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	914	—	pF	$\text{V}_{\text{DS}} = 6\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$, $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	132	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	119	—	pF	
Gate Resistance	R_g	—	1.26	—	Ω	
Total Gate Charge ($\text{V}_{\text{GS}} = 4.5\text{V}$)	Q_g	—	10.5	—	nC	$\text{V}_{\text{DS}} = 6\text{V}$, $\text{I}_D = 6.5\text{A}$
Total Gate Charge ($\text{V}_{\text{GS}} = 8\text{V}$)		—	19.6	—	nC	
Gate-Source Charge	Q_{gs}	—	1.2	—	nC	
Gate-Drain Charge	Q_{gd}	—	1.6	—	nC	
Turn-On Delay Time	$\text{t}_{\text{D(ON)}}$	—	5.0	—	ns	
Turn-On Rise Time	t_r	—	10.5	—	ns	$\text{V}_{\text{DD}} = 6\text{V}$, $\text{V}_{\text{GS}} = 4.5\text{V}$, $\text{R}_L = 1.2\Omega$, $\text{R}_G = 1\Omega$
Turn-Off Delay Time	$\text{t}_{\text{D(OFF)}}$	—	16.6	—	ns	
Turn-Off Fall Time	t_f	—	4.1	—	ns	

Electrical Characteristics Q2 P-CHANNEL (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	-1.0	μA	$\text{V}_{\text{DS}} = -12\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$\text{V}_{\text{GS}} = \pm 8\text{V}$, $\text{V}_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$\text{V}_{\text{GS(TH)}}$	-0.4	—	-1	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$, $\text{I}_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	—	37	61	mΩ	$\text{V}_{\text{GS}} = -4.5\text{V}$, $\text{I}_D = -3.6\text{A}$
		—	47	81		$\text{V}_{\text{GS}} = -2.5\text{V}$, $\text{I}_D = -3.2\text{A}$
		—	63	115		$\text{V}_{\text{GS}} = -1.8\text{V}$, $\text{I}_D = -1\text{A}$
		—	90	210		$\text{V}_{\text{GS}} = -1.5\text{V}$, $\text{I}_D = -1\text{A}$
Diode Forward Voltage	V_{SD}	—	-0.65	-1.2	V	$\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_S = -1\text{A}$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	915	—	pF	$\text{V}_{\text{DS}} = -6\text{V}$, $\text{V}_{\text{GS}} = 0\text{V}$, $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	225	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	183	—	pF	
Gate Resistance	R_g	—	56.9	—	Ω	
Total Gate Charge ($\text{V}_{\text{GS}} = -4.5\text{V}$)	Q_g	—	10.7	—	nC	$\text{V}_{\text{DS}} = -6\text{V}$, $\text{I}_D = -4.3\text{A}$
Total Gate Charge ($\text{V}_{\text{GS}} = -8\text{V}$)		—	17.9	—	nC	
Gate-Source Charge	Q_{gs}	—	1.7	—	nC	
Gate-Drain Charge	Q_{gd}	—	3.0	—	nC	
Turn-On Delay Time	$\text{t}_{\text{D(ON)}}$	—	5.7	—	ns	
Turn-On Rise Time	t_r	—	11.5	—	ns	$\text{V}_{\text{DD}} = -6\text{V}$, $\text{V}_{\text{GS}} = -4.5\text{V}$, $\text{R}_L = 1.6\Omega$, $\text{R}_G = 1\Omega$
Turn-Off Delay Time	$\text{t}_{\text{D(OFF)}}$	—	27.8	—	ns	
Turn-Off Fall Time	t_f	—	26.4	—	ns	

Notes: 6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

Typical Characteristics - N-CHANNEL

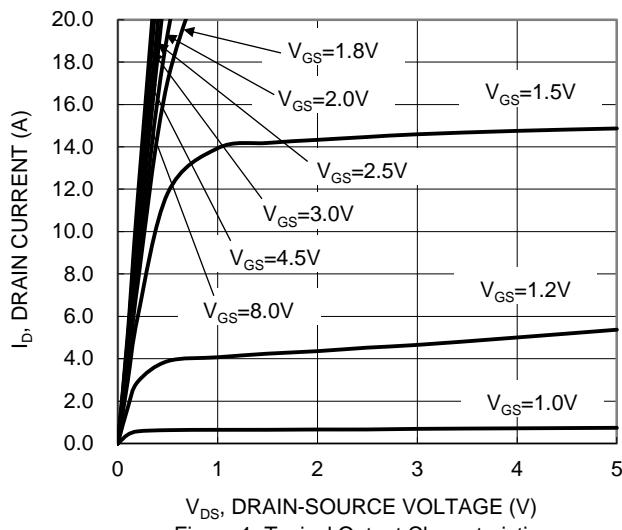


Figure 1. Typical Output Characteristic

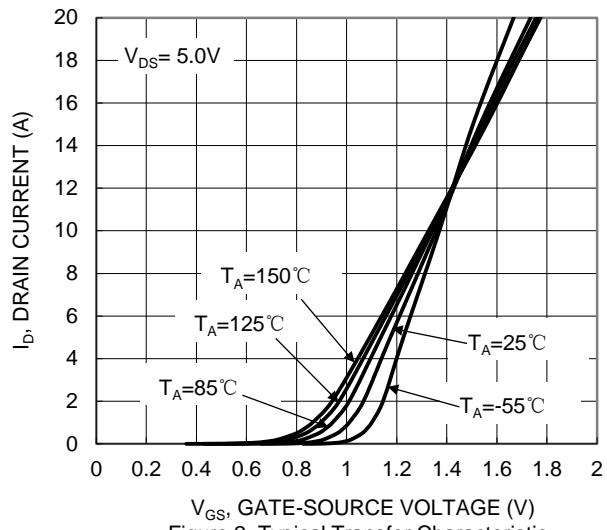


Figure 2. Typical Transfer Characteristic

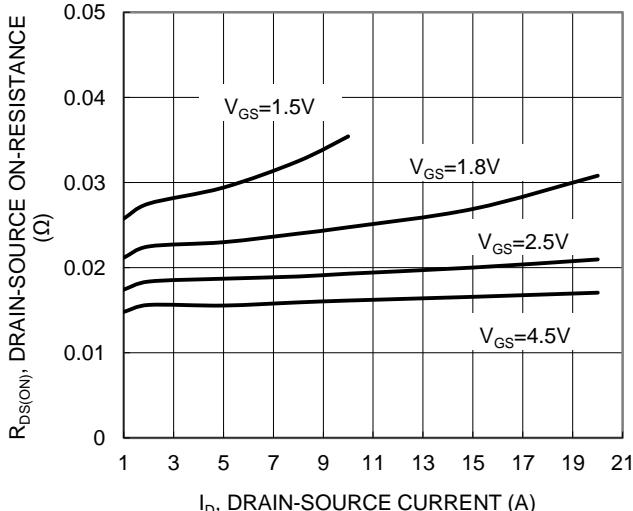


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

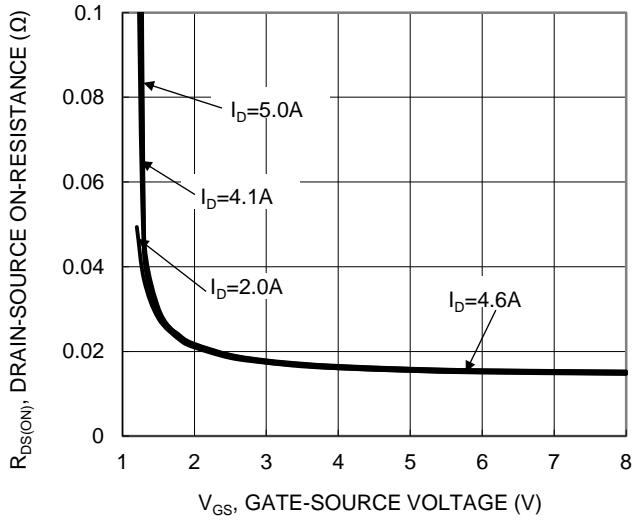


Figure 4. Typical Transfer Characteristic

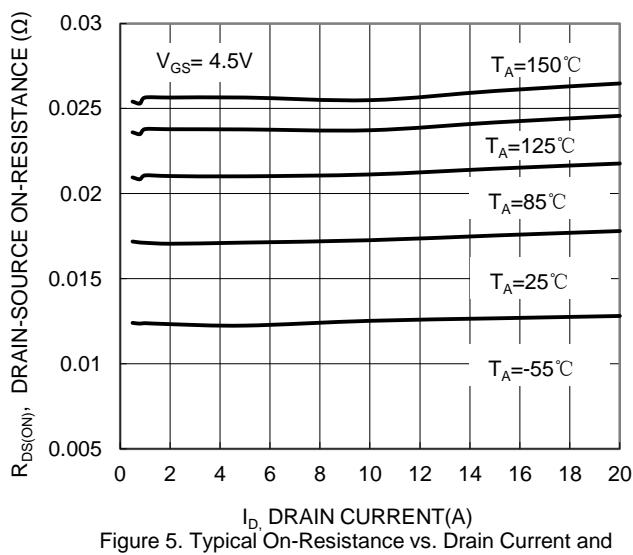


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

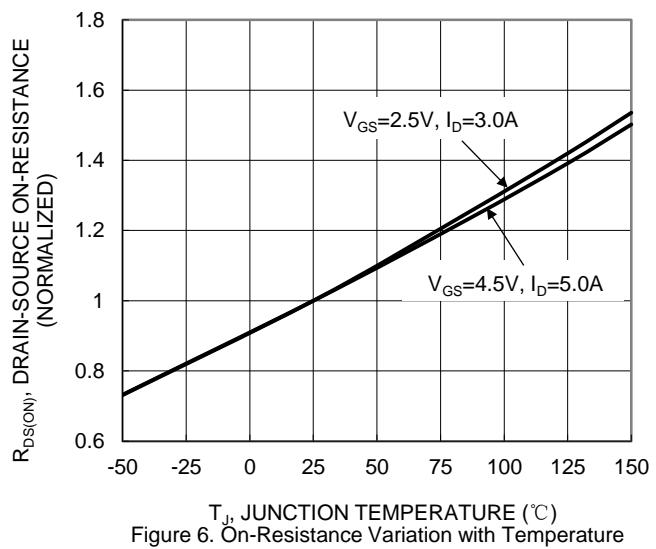
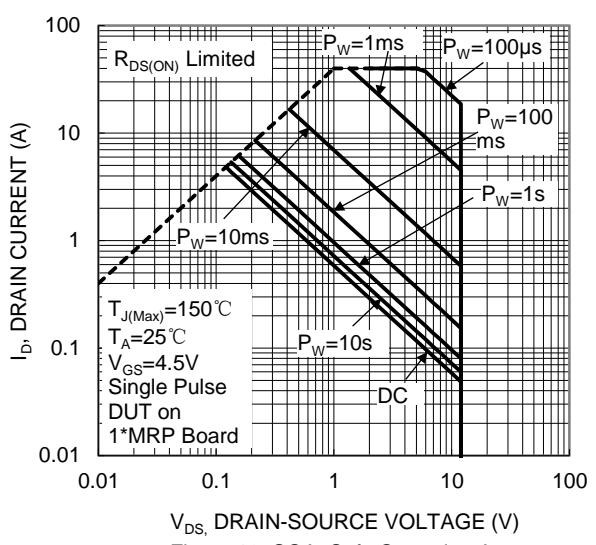
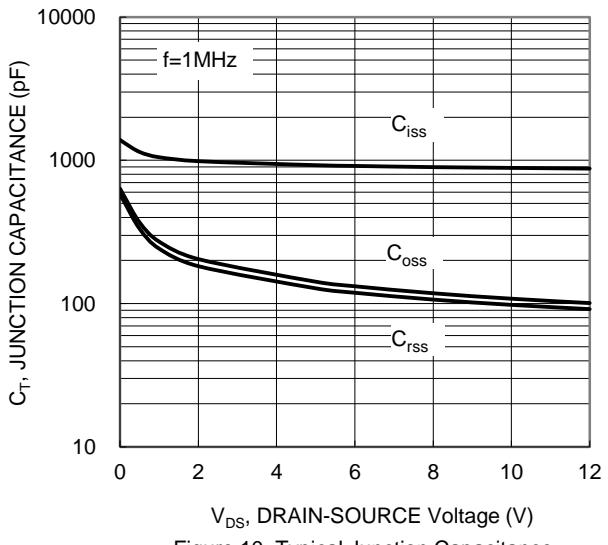
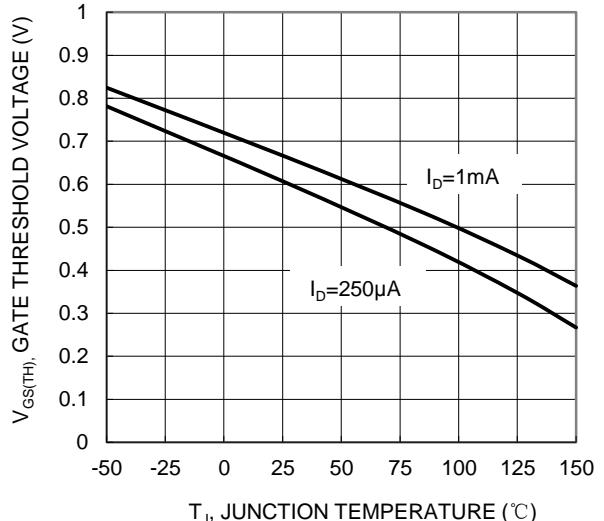
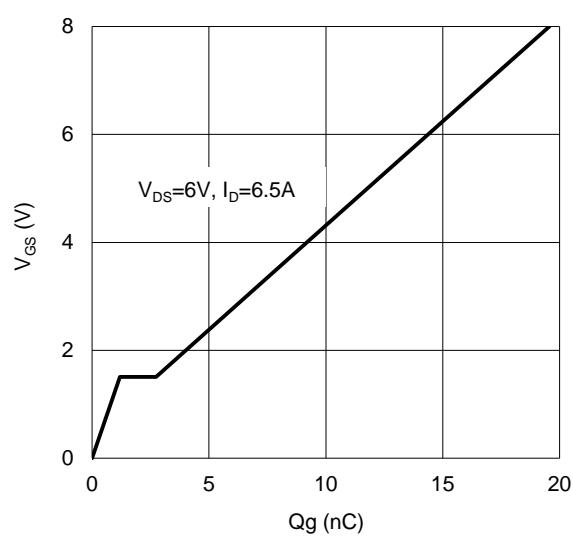
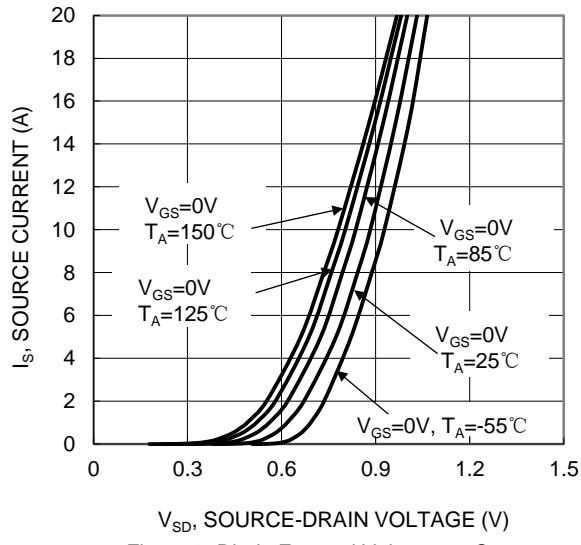
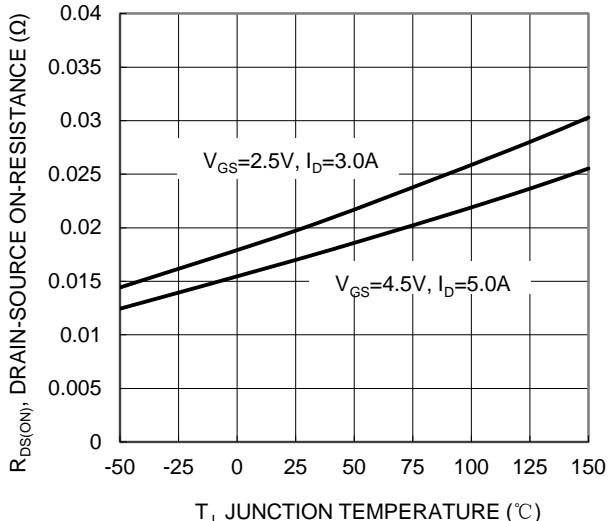


Figure 6. On-Resistance Variation with Temperature



Typical Characteristics - P-CHANNEL

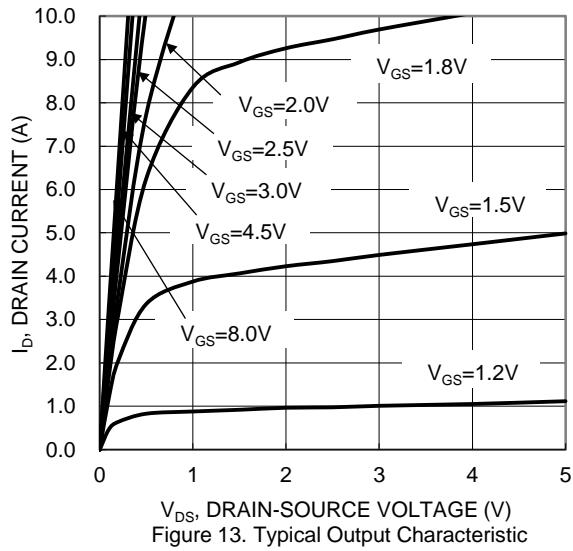


Figure 13. Typical Output Characteristic

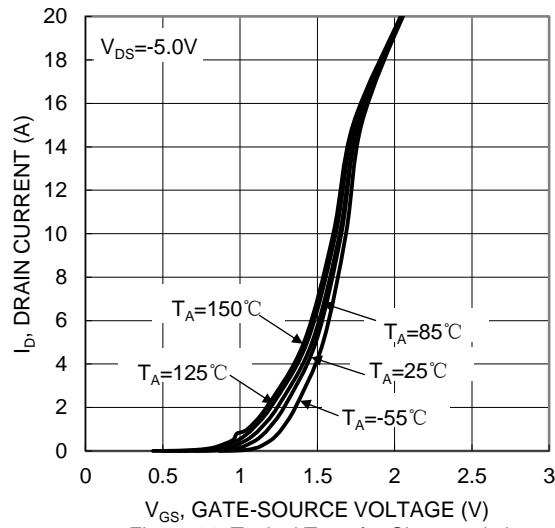


Figure 14. Typical Transfer Characteristic

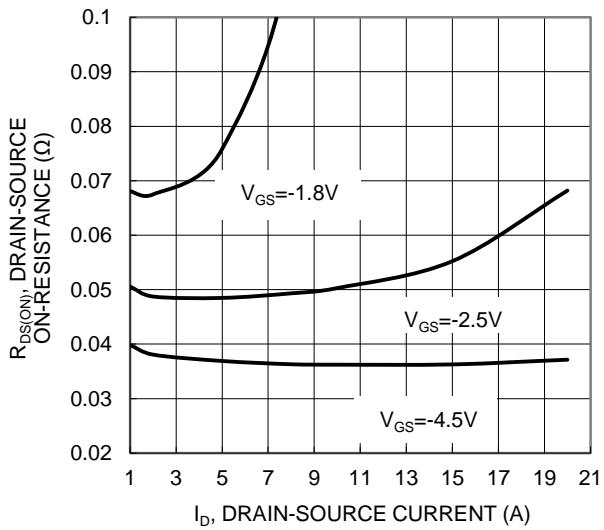


Figure 15. Typical On-Resistance vs Drain Current and Gate Voltage

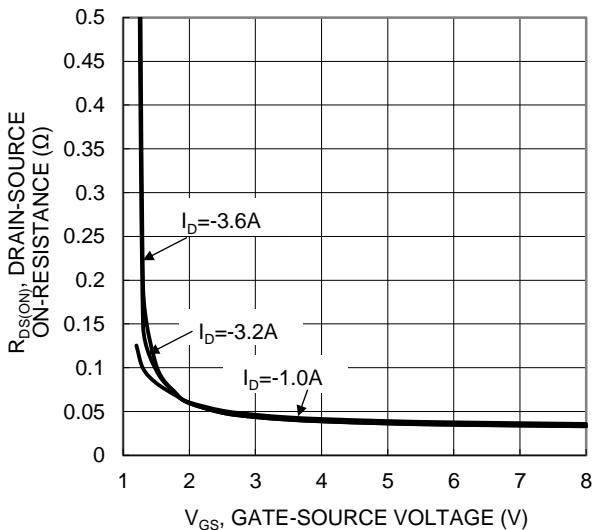


Figure 16. Typical Transfer Characteristic

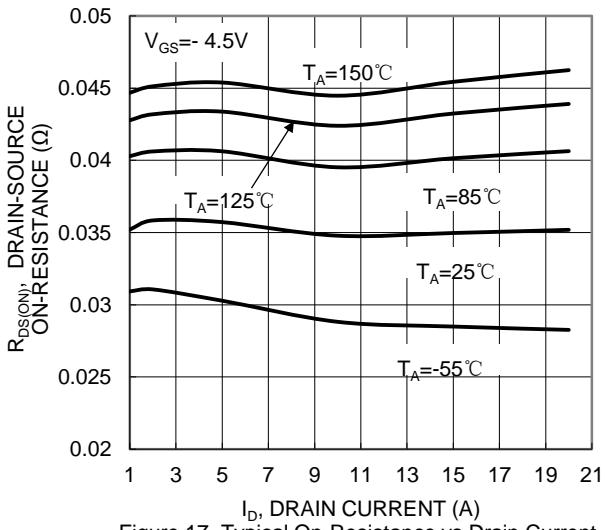


Figure 17. Typical On-Resistance vs Drain Current and Temperature

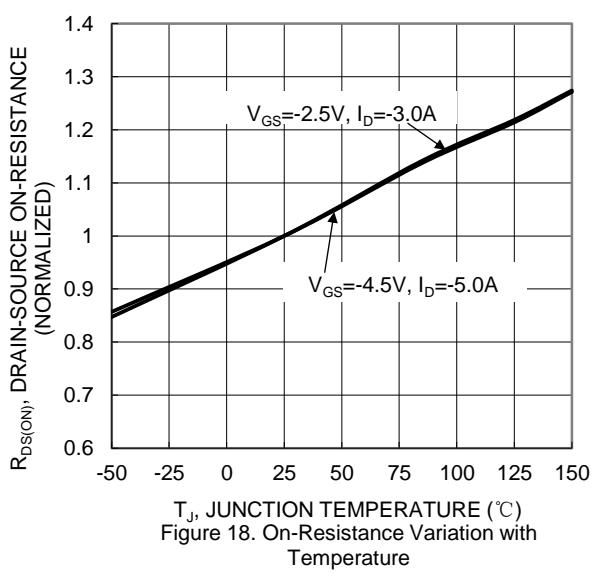
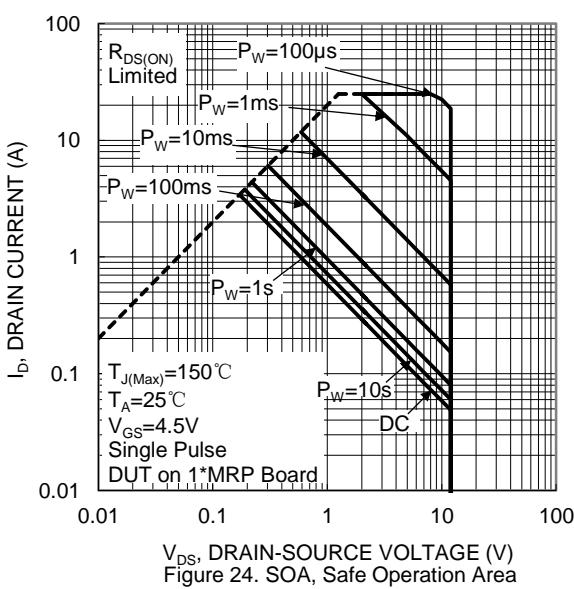
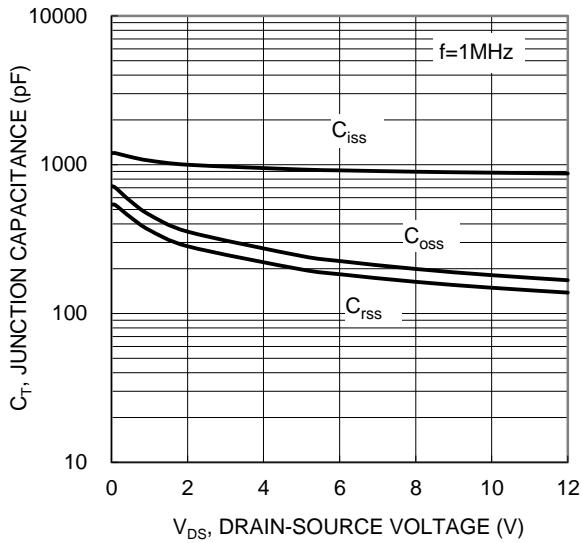
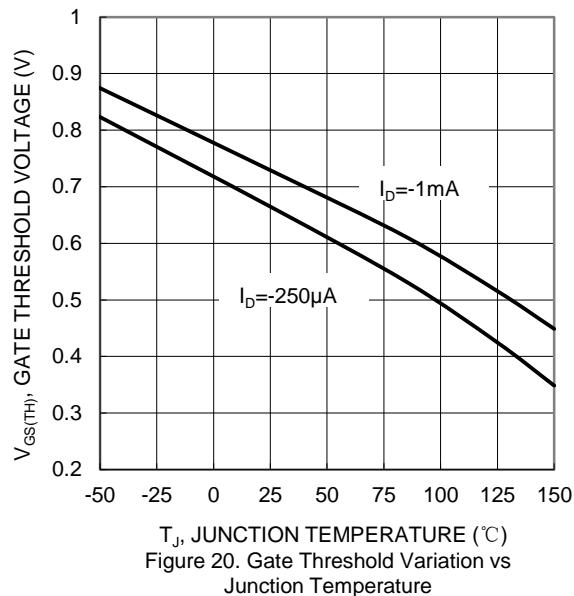
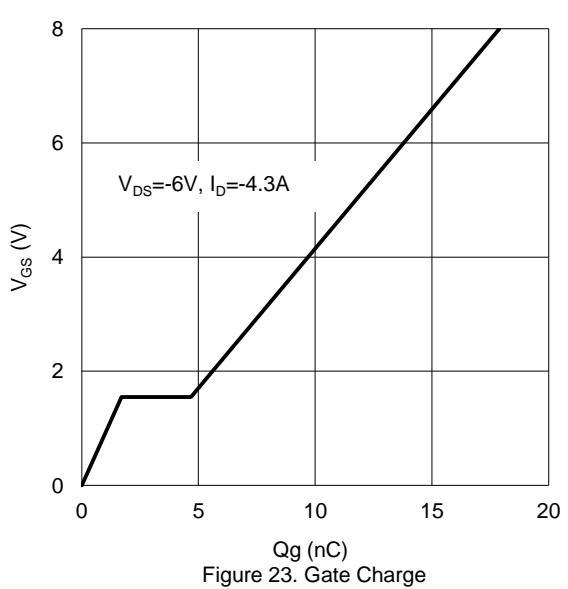
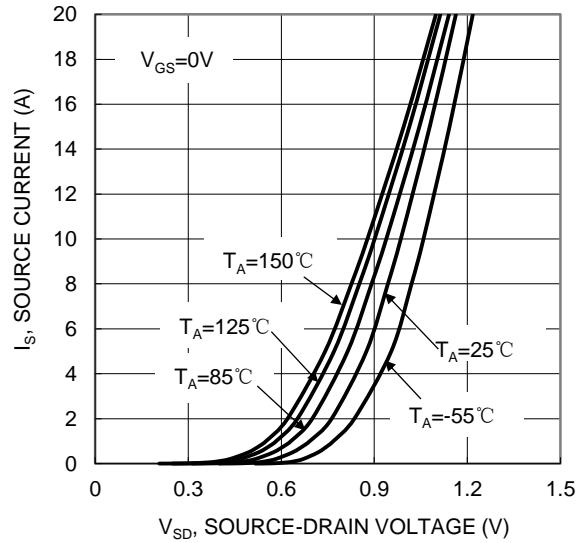
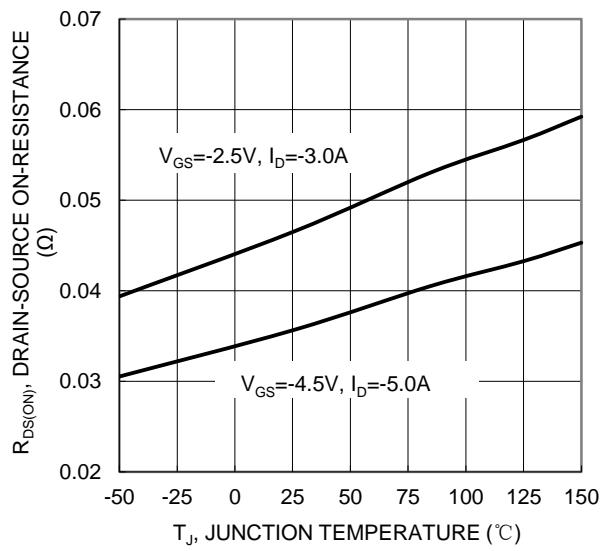


Figure 18. On-Resistance Variation with Temperature



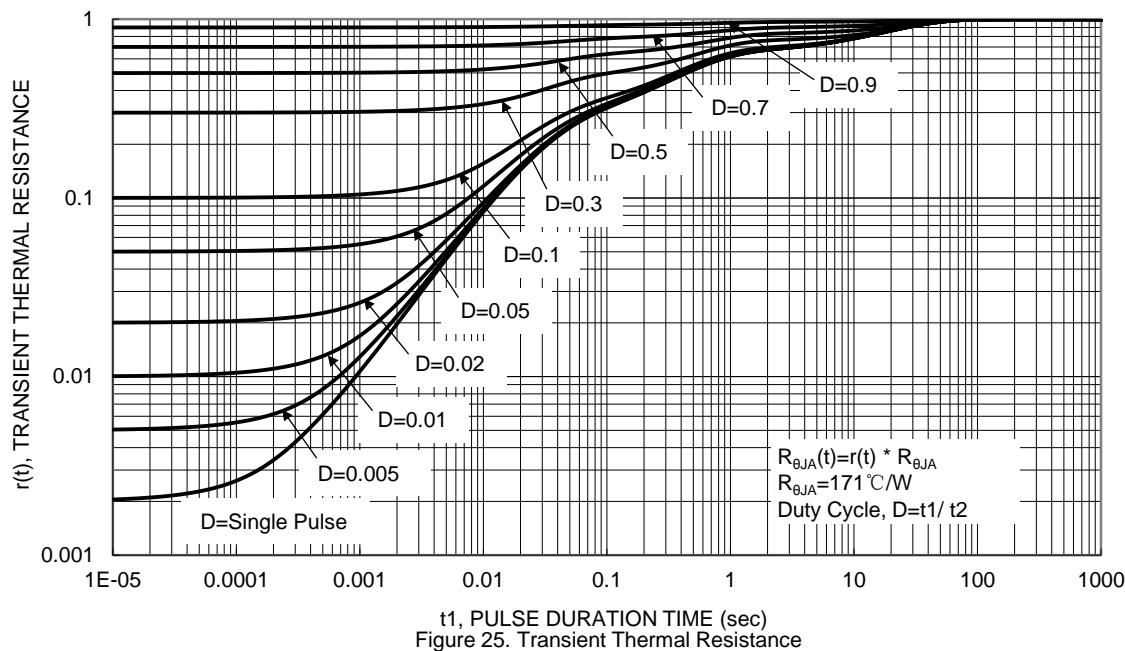
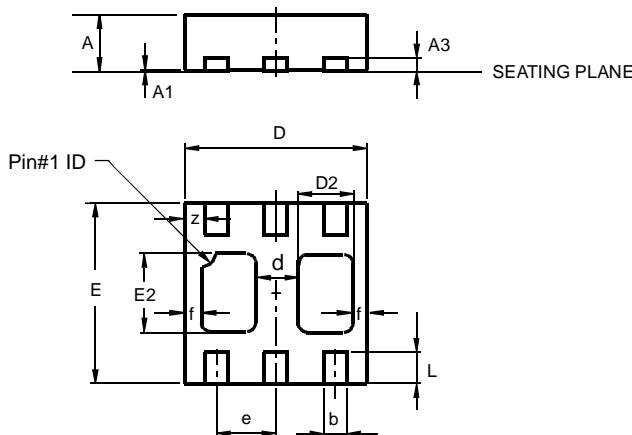


Figure 25. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

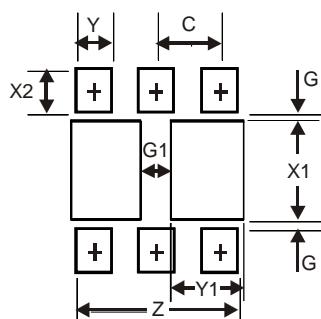


U-DFN2020-6 Type B			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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